

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	9	punsalan near david.in.	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
2	BRS	L2	23	lazaroff near dennis.in.	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
3	BRS	L3	48	beatty near christopher.in.	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
4	BRS	L4	24330	((liquid near5 film) near25 (substrate or wafer))	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

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5	BRS	L5	3743	((liquid near film) near25 (substrate or wafer))	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
6	BRS	L6	191	(pattern\$3 or etch\$3) near15 ((liquid near film) near25 (substrate or wafer))	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
7	BRS	L7	0	((pattern\$3 or etch\$3) near15 ((liquid near film) near25 (substrate or wafer))) near15 (ceramic)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
8	BRS	L8	18	((pattern\$3 or etch\$3) near15 ((liquid near film) near25 (substrate or wafer))) and (ceramic)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
9	BRS	L10	6	((pattern\$3 or etch\$3) near15 ((liquid) near3 (solution or film) near25 (substrate or wafer))) near25 (ceramic)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
10	BRS	L9	188	((pattern\$3 or etch\$3) near15 ((liquid) near3 (solution or film) near25 (substrate or wafer))) and (ceramic)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
11	BRS	L11	546	(pattern\$3 near3 ceramic near3 film)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
12	BRS	L12	255	((pattern\$3 near3 ceramic near3 film)) near25 (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
13	BRS	L13	255	((pattern\$3 near3 ceramic near3 film)) near25 (substrate or wafer)) nea25 (liquid near 3film)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
14	BRS	L14	81941	((pattern\$3 near3 ceramic near3 film)) near25 (substrate or wafer)) nea25 (liquid near3 film)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
15	BRS	L15	81941	((pattern\$3 near3 ceramic near3 film) near25 (substrate or wafer)) nea25 ((liquid near3 film))	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
16	BRS	L16	30292	((pattern\$3 near3 ceramic near3 film) near25 (substrate or wafer)) nea25 (liquid near film)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
17	BRS	L17	1856	((pattern\$3 near3 ceramic near3 film) near25 (substrate or wafer)) nea25 (heat\$3) near5 (liquid near film)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
18	BRS	L18	256	((pattern\$3 near3 ceramic near3 film) near25 (substrate or wafer)) nea25 (heat\$3) near5 (liquid near film) near25 (metal near3 salt)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
19	BRS	L19	1856	((pattern\$3 near3 ceramic near3 film) near25 (substrate or wafer)) nea25 (heat\$3) near5 (liquid near film)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
20	BRS	L21	1	((pattern\$3 near3 ceramic near3 film) near25 (substrate or wafer)) nea25 (heat\$3) near5 (liquid near film)) near15 (metal near salt)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
21	BRS	L22	7	((pattern\$3 near3 ceramic near3 film) near25 (substrate or wafer)) nea25 (heat\$3) near5 (liquid near film)) near15 (photoresist)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
22	BRS	L20	1856	((pattern\$3 near3 ceramic near3 film) near25 (substrate or wafer)) nea25 (heat\$3) near5 (liquid near film))	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
23	BRS	L23	1671	((pattern\$3 near ceramic near3 film) near25 (substrate or wafer)) nea25 (heat\$3) near5 (liquid near film))	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
24	BRS	L24	1618	((pattern\$3 near ceramic near film) near25 (substrate or wafer)) nea25 (heat\$3) near5 (liquid near film))	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
25	BRS	L25	31	((pattern\$3 near ceramic near film) near25 (substrate or wafer)) nea25 (heat\$3) near5 (liquid near film)) near15 (liquid near3 solution)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
26	BRS	L26	0	((pattern\$3 near ceramic near film) near25 (substrate or wafer)) near5 (liquid near film)) near15 (liquid near3 solution)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
27	BRS	L27	0	((pattern\$3 near ceramic near film) near25 (substrate or wafer)) near15 (liquid near3 solution)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
28	BRS	L28	0	((pattern\$3 near ceramic near film) near25 (substrate or wafer)) near15 (liquid near5 solution)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
29	BRS	L29	17	((pattern\$3 near ceramic near film) near25 (substrate or wafer))	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
30	BRS	L30	24	((pattern\$3 oe etch\$3) near (ceramic near film)) near25 (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
31	BRS	L31	17	((pattern\$3 or etch\$3) near (ceramic near film)) near25 (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
32	BRS	L32	1744	(ceramic near film) near25 (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
33	BRS	L33	1	(liquid near film) near15 (ceramic near film) near25 (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
34	BRS	L34	17	(liquid near5 film) near15 (ceramic near film) near25 (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
35	BRS	L35	184	(liquid near5 film) near15 (ceramic) near25 (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	U	1	Document ID	Title
1			US 20030181122 A1	Producing self-aligned and self-exposed photoresist patterns on light emitting devices
2			US 6756186 B2	Producing self-aligned and self-exposed photoresist patterns on light emitting devices
3			US 6265139 B1	Method for fabricating piezoelectric/electrostrictive ceramic micro actuator using photolithography
4			US 6074893 A	Process for forming fine thick-film conductor patterns
5			US 5763123 A	Method for producing thin-film substrate
6			US 4789425 A	Thermal ink jet printhead fabricating process
7	X		JP 07062592 A	PRODUCTION OF THIN-FILM MAGNETIC HEAD